

Printed circuit board material with high workability - contains insulation board composed of layer made with polyphenylene oxide resin compsn. contg. crosslinkable polymer and/or monomer

Patent Assignee: MATSUSHITA ELECTRIC WORKS LTD (MATW)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 63224940	A	19880920	JP 8759719	A	19870315	198843 B
JP 93064586	B	19930914	JP 8759719	A	19870315	199339

Priority Applications (No Type Date): JP 8759719 A 19870315

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 63224940	A	9			
JP 93064586	B	10		B32B-027/04	Based on patent JP 63224940

Abstract (Basic): JP 63224940 A

Printed circuit board contains an insulation board which is composed of a layer made with a polyphenylene oxide resin compsn. contg. a polyphenylene oxide, a crosslinkable polymer and/or a crosslinkable monomer, and an inorganic filler, and a layer of a base material impregnated with a resin but not the polyphenylene oxide resin compsn.

Polyphenylene oxide is pref. poly (2,6-dimethyl-1,4-phenylene oxide), etc. Crosslinkable polymer is 1,2-polybutadiene, styrene-butadiene copolymer, etc. Crosslinkable monomer is tri-allycyanurate and/or triallylisocyanurate, etc. Inorganic filler is Al oxide, SiO₂, TiO₂, etc. Base material is cloth of glass, aramid, polyester, etc. Resin for impregnation is epoxy resin, polyimide resin, etc.

USE/ADVANTAGE - The material is useful for printed-circuit boards applicable in UHF and SHF bands. The printed-circuit board is superior in permittivity (i.e., 10.8 (1M Hz) in contrast to 9.8 using copper clad alumina insulation base board), and workability for drilling, etc.

Title Terms: PRINT; CIRCUIT; BOARD; MATERIAL; HIGH; WORK; CONTAIN; INSULATE ; BOARD; COMPOSE; LAYER; MADE; POLYPHENYLENE; OXIDE; RESIN; COMPOSITION; CONTAIN; CROSSLINK; POLYMER; MONOMER

Derwent Class: A18; A25; A85; L03; P73; V04

International Patent Class (Main): B32B-027/04

International Patent Class (Additional): B32B-015/08; C08J-005/24; H05K-001/03

File Segment: CPI; EPI; EngPI

?